



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-19
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T2035T-8G	7BD1*208SAM1	A	3068	2018-09-19
Amount	UoM	Unit type	ST ECOPACK Grade	
1600.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	D2PAK CLIP; MDF vlid also for T2035T-8G-TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-l	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: — glass in bulbs and glaze of spark plugs, — dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.42	Die	264
Lead	38.84	Die - Soft solder	24272
Lead-Borate Glass	1.96	Die	1226

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	36.874	Die - Soft solder	23046
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	28.486	Die	713720
Lead	1000 ppm	8.388	Soft solder	920241

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	78D1*208SAM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	39.912	mg	supplier	die	Silicon (Si)	7440-21-3		8.947	mg	224168	5592
				supplier	metallization	Gold (Au)	7440-57-5		0.034	mg	852	21
				supplier	metallization	Nickel (Ni)	7440-02-0		0.179	mg	4485	112
				JIG - R	Passivation	Lead (Pb)	7439-92-1	7a-Lead in high mel	28.486	mg	713720	17804
				supplier	Passivation	Silicon Oxide	7631-86-9		0.051	mg	1278	32
				supplier	back side metallization	Gold (Au)	7440-57-5		0.011	mg	276	7
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.243	mg	6088	152
Leadframe	M-004 Copper and its alloys	700.749	mg	JIG-R & California 65	glass coating	Lead-Borate Glass	65997-18-4		1.961	mg	49133	1223
				supplier	alloy	Copper (Cu)	7440-50-8		699.838	mg	998700	437399
				supplier	alloy	Iron (Fe)	7439-89-6		0.701	mg	1000	438
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.210	mg	300	131
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	8.388	mg	920241	5243
Soft solder	Soldier	9.115	mg	supplier	solder	Silver (Ag)	7440-22-4		0.227	mg	24904	142
				supplier	solder	Tin (Sn)	7440-31-5		0.454	mg	49808	284
				supplier	solder	flux residue	Proprietary		0.046	mg	5047	29
Encapsulation	M-011 Other inorganic materials	812.285	mg	supplier	mold compound	Silica, vitreous	60676-86-0		617.337	mg	760000	385836
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		82.853	mg	102000	51783
				supplier	mold compound	Phenol resin	9003-35-4		48.737	mg	60000	30461
				supplier	mold compound	Others	Proprietary		40.614	mg	50000	25384
				supplier	mold compound	Metal hydroxide	Proprietary		16.246	mg	20000	10154
				supplier	mold compound	Carbon black	1333-86-4		6.498	mg	8000	4061
connections coating	Soldier	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3946
Clip	M-004 Copper and its alloys	31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	19766